



Material Content Data Sheet



Sales Product Name		IPG20N10S4-36A		Issued		1. August 2018		
MA#		MA002213672						
Package		PG-TDSON-8-10		Weight*		98.81 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	1.057	1.07	1.07	10695	10695
chip_2	inorganic material	silicon	7440-21-3	1.057	1.07	1.07	10695	10695
leadframe	inorganic material	phosphorus	7723-14-0	0.014	0.01		141	
	non noble metal	iron	7439-89-6	0.046	0.05		470	
	non noble metal	copper	7440-50-8	46.380	46.94	47.00	469391	470002
	non noble metal	aluminium	7429-90-5	0.814	0.82	0.82	8234	8234
wire	non noble metal	aluminium	7429-90-5	0.814	0.82	0.82	8234	8234
encapsulation	organic material	carbon black	1333-86-4	0.090	0.09		908	
	plastics	epoxy resin	-	6.371	6.45		64480	
	inorganic material	silicondioxide	60676-86-0	38.407	38.87	45.41	388696	454084
leadfinish	non noble metal	tin	7440-31-5	1.396	1.41	1.41	14132	14132
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		15	
	non noble metal	nickel	7440-02-0	0.603	0.61	0.61	6103	6118
solder	non noble metal	tin	7440-31-5	0.051	0.05		521	
	noble metal	silver	7440-22-4	0.064	0.07		651	
	non noble metal	lead	7439-92-1	2.457	2.49	2.61	24868	26040
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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